



<b>Information Disclosure Statement By Applicant</b>  (Use Several Sheets if Necessary)	Atty. Docket No. NVIDP234/P000825	Application No.: 10/633,004
	Applicant: Singh et al. Filing Date: 7/31/2003	Group Art Unit: Unassigned 2811

#### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
Vu	A	6,538,326	03/25/2003	Shimizu et al.	257	758	10/4/2001
	B	6,552,438	04/22/2003	Lee et al.	257	784	12/21/2000
	C	5,965,903	10/12/1999	Chittipeddi et al.	257	48	02/12/1998
	D	6,297,562	10/02/2001	Tilly	257	780	09/20/1999
	E	6,232,662	05/15/2001	Saran	257	750	07/02/1999
	F	6,365,970	04/02/2002	Tsai et al.	257	751	12/10/1999
	G	6,417,087	07/09/2002	Chittipeddi et al.	438	612	12/16/1999
	H	4,636,832	01/13/1987	Abe et al.	357	68	03/04/1986
	I	4,723,197	02/02/1988	Takiar et al.	361	403	12/16/1985
	J	6,100,589	08/08/2000	Tanaka	257	758	08/19/1997
	K	4,984,061	01/08/1991	Matsumoto	357	68	05/10/1988
	L	6,384,486	05/07/2002	Zuniga et al.	257	781	12/10/1999
	M	6,400,026	06/04/2002	Andou et al.	257	771	06/26/2000
	N	6,489,228	12/03/2002	Vigna et al.	438	612	10/02/2000
	O	6,358,831	03/19/2002	Liu et al.	438	612	03/03/1999
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	S	5,773,899	06/30/1998	Zambrano	257	784	08/29/1996
	T	6,144,100	11/07/2000	Shen et al.	257	762	10/28/1997
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#### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	V	Heinen, Gail et al., "Wire Bonds Over Active Circuits", 1994, IEEE
*	W	Chou, Kuo-Yu et al., "Active Circuits Under Wire Bonding I/O Pads in 0.13 $\mu$ m Eight-Level Cu Metal, FSG Low-K Inter-Metal Dielectric CMOS Technology +", October 2001, IEEE
*	X	Efland, T., et al., "LeadFrameOnChip offers Integrated Power Bus and Bond over Active Circuit", 2001, International Symposium on Power Semiconductor Devices & ICs, Osaka
Examiner	HUNG VU	
Date Considered	10/05/04	

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



<b>Form 1449 (Modified)</b>  <b>Information Disclosure Statement By Applicant</b>  (Use Several Sheets if Necessary)	Atty. Docket No.	Application No.:
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	Singh et al.	
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		Unassigned 281

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Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
<u>N</u>	Y	6,448,641	09/10/2002	Ker et al.	257	700	06/09/1999
	Z	6,486,051	11/26/2002	Sabin et al.	438	612	03/17/1999
	AA	6,489,688	12/03/2002	Baumann et al.	257	786	05/02/2001
	BB	6,087,732	07/11/2000	Chittipeddi et al.	257	786	09/28/1998
	CC	5,027,188	06/25/1991	Owada et al.	357	68	09/13/1989
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	GG						
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#### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
<u>N</u>	TT	Saran, Mukul et al., "Elimination of Bond-pad Damage Through Structural Reinforcement of Intermetal Dielectrics", 1998, IEEE 36th Annual International Reliability Physics Symposium, Reno, Nevada
Examiner HUNG VU		Date Considered 10/05/04

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